

IN THE CLAIMS:

Please amend the claims as follows:

1. (Currently Amended) A method of enhancing adhesion of a compound to a surface of a substrate comprising:
providing the substrate having the surface;
scanning the substrate for irregularities for removal; and
roughening the surface of the substrate for removal of irregularities.
2. (Previously Presented) The method according to claim 1, wherein roughening comprises removing contamination and foreign particles from the surface of the substrate.
3. (Currently Amended) A method of enhancing adhesion of a material to a surface of a substrate comprising:
providing the substrate having the surface;
scanning the substrate for irregularities for removal; and
roughening the surface of the substrate while removing irregularities.
4. (Previously Presented) The method according to claim 3, wherein roughening comprises removing contamination and foreign particles from the surface of the substrate.
5. (Currently Amended) A method for improving adhesion of a compound to a surface of a substrate comprising:
providing the substrate having the surface;
scanning the substrate for irregularities for removal; and
roughening the surface of the substrate.
6. (Previously Presented) The method according to claim 5, wherein roughening comprises removing contamination and foreign particles from the surface of the substrate.